Concurrent Technologies announces support for the latest Intel® Xeon® mobile processors and launches a 6U VPX™ board

Concurrent Technologies launches VR E7x/msd, a new 6U VPX™ computing board based upon the newly announced launch of the Intel® Xeon® processor E-2176M (formerly known as Coffee Lake-H). Supporting 50% more processor cores within the same power envelope, the Intel Xeon processor E-2176M has six-cores compared to previous generation quad-core processors from the same product family. In addition to the launch of VR E7x/msd 6U VPX board, Concurrent Technologies is introducing the same processor across a number of other form factors including VMEbus. Further announcements will follow as boards are officially released.

In addition to improved processing capability, VR E7x/msd includes the option of front panel mounted USB 3.1 ports, 10 Gigabit Ethernet connectivity, enhanced storage options and improved digital graphics outputs. Direct attached storage options include a SATA flash disk and two M.2 modules. These utilize PCI Express® connectivity and NVMe support for a high capacity solution that is suitable for use in challenging environments. VR E7x/msd is designed to fulfil a system management role for high performance 6U VPX processing solutions and so includes the option for dual XMC modules to support I/O expansion.

Initial shipments of the product will be air-cooled, with production quantities expected in Q3. A conduction-cooled version designed to meet an operating temperature range of -40°C to +85°C will be available after further qualification testing. Initial operating system support will be for Linux® and Windows® with optional support for others such as VxWorks® will follow based on customer demand.

Glen Fawcett, CEO of Concurrent Technologies, commented:" From our inception in 1985, we have based our product line on Intel's roadmap and launches of the latest embedded processors. Our new 6U VPX product announcement further demonstrates this commitment to launch cutting edge products as early as possible in the silicon life-cycle to meet our customer requirements."